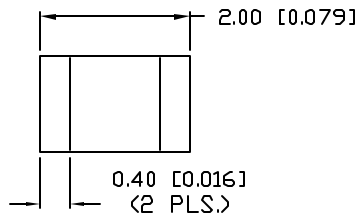
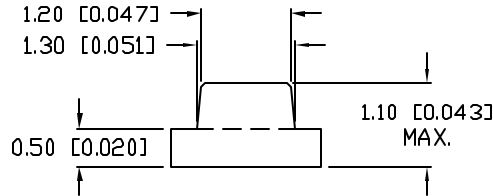
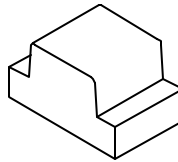
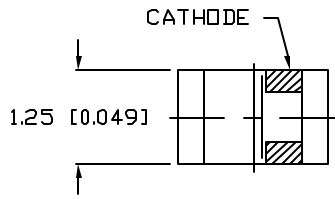


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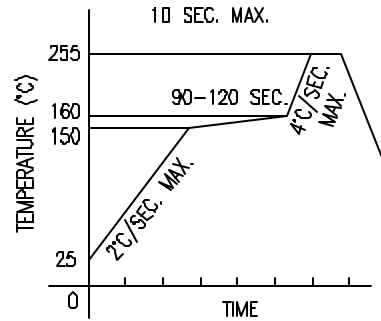
PART NUMBER
SML-LXF0805UPGC-TR

REV.
B

CAUTION: STATIC SENSITIVE DEVICE
FOLLOW PROPER E.S.D. HANDLING PROCEDURES
WHEN WORKING WITH THIS PART.



LEAD FREE REFLOW PROFILE



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		525		nm	
FORWARD VOLTAGE		3.4	4.0	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_r=100\mu\text{A}$
AXIAL INTENSITY		80		mod	$I_f=20\text{mA}$
VIEWING ANGLE		120		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

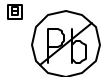
PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	160	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-30 TO +85	°C
STORAGE TEMP.	-40 TO +85	°C

* $t < 10\mu\text{s}$

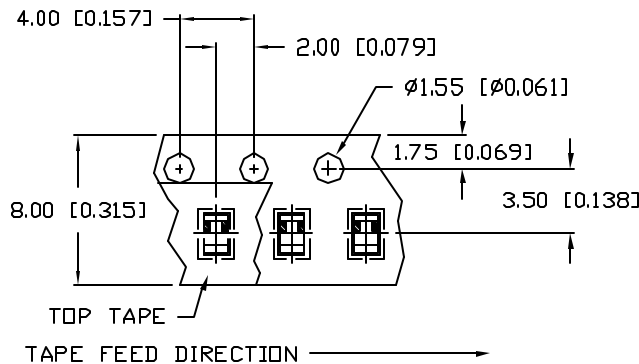
NOTES:

- THE POLARITY MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

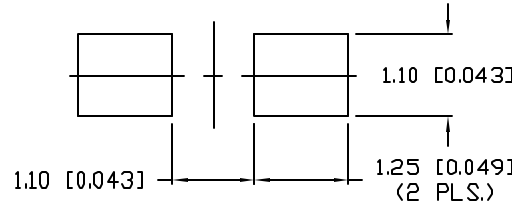
CAUTION: MOISTURE SENSITIVE DEVICE
PER JEDEC LEVEL 4 STANDARDS



UNCONTROLLED DOCUMENT



RECOMMENDED SOLDER PAD LAYOUT



*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030). MIN.=^{+DECIMAL PRECISION}-0.00 MAX.=^{+0.00}-DECIMAL PRECISION

REV.
B

PART NUMBER
SML-LXF0805UPGC-TR

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2.0mm x 1.25mm SURFACE MOUNT LED,
525nm ULTRA PURE GREEN LED,
WATER CLEAR LENS, TAPE AND REEL

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC	CHECKED BY:	APPROVED BY:	DATE: 1.12.01
			PAGE: 1 OF 1
			SCALE: N/A